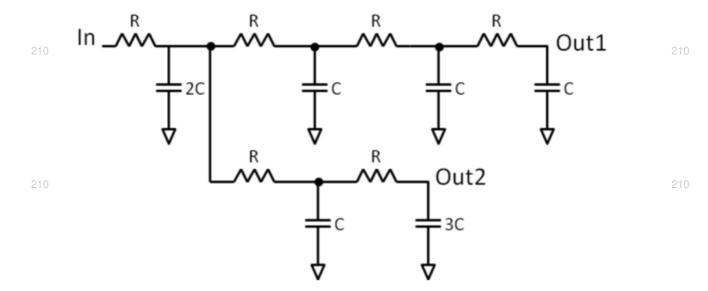
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## Part-III

Only Long Answer Type Questions (Answer Any Two out of Four)

- Q3 a) Why mask layouts are of much importance in VLSI IC fabrication.
   (8)
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- Q4 a) Explain about Elmore delay model used for finding delay in the circuit branches. (8)
  - b) For the below circuit, with R = 100 ohm and C = 10 femto Farad, calculate the Elmore delay from In to Out1 and Out2. Which path is critical path.



- Q5 a) Write a detailed note on True Single Phase Clocked Register(TSPCR) ciruits. (8)
  - b) Consider a CMOS inverter circuit which contains following parameters :  $V_{DD} = 3.3 \text{ V}$ ,  $V_{To,n} = 0.6 \text{ V}$ ,  $V_{To,p} = -0.7 \text{ V}$ ,  $K_n = 200 \text{ }\mu\text{A} \text{ /V}^2$ ,  $K_p = 80 \text{ MeV}$ 
    - (a) Find the noise margin of the circuit for logic high with proper derivation of parameters.
    - (b) Find the noise margin of the circuit for logic low with proper derivation of parameters.
- Q6 a) How does DRAMs(Dynamic RAM) are able to provide a higher packing density as compared to SRAMs? Explain.
  - **b)** What is the clock overlap condition in C<sup>2</sup>MOS circuits? Describe the situation for a (5) (1,1) clock overlap case with suitable diagram.
  - c) What function does a PRPG(Pseudo Random Patten Generator) perform in testing of VLSI ICs. (6)

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